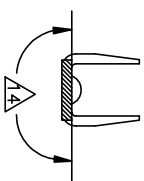
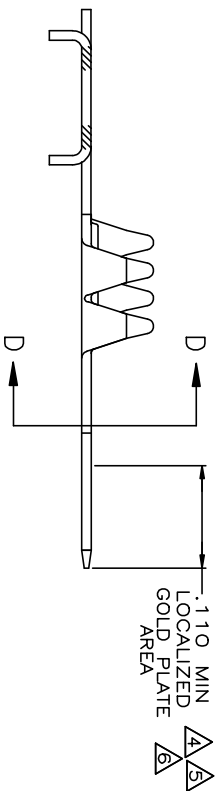
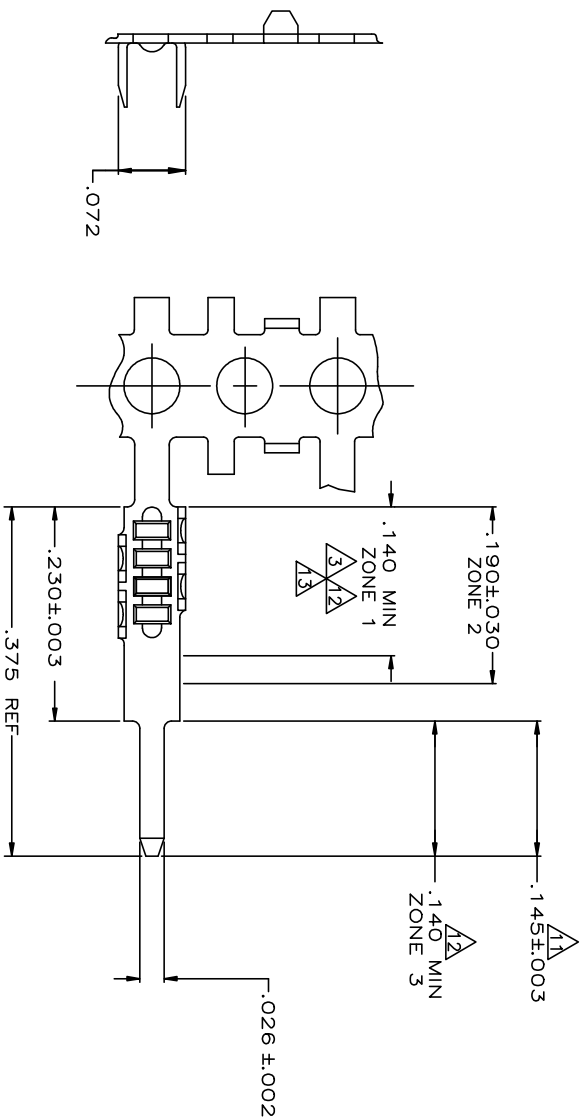


REVISIONS				
P	CHK	DESCRIPTION	DATE	BY
12		REVISED PER ECR-23-193756	01DEC2023	GC WH



SECTION D-D

- 1. .000050 MIN THK NICKEL UNDERPLATE OVER ENTIRE CONTACT.
- 2. .000150 MIN BRIGHT TIN/LEAD OVER ENTIRE CONTACT.
- 3. .000100 MIN THK BRIGHT TIN/LEAD IN ZONE 1.
- 4. GOLD FLASH IN LOCALIZED GOLD PLATE AREA.
- 5. .000015 MIN GOLD IN LOCALIZED GOLD PLATE AREA
- 6. .000030 MIN GOLD IN LOCALIZED GOLD PLATE AREA
- 7. TO BE APPLIED PER AMP APPLICATION SPEC 114-16015.
- 8. RECOMMENDED HOLE SIZE IS .031-.035 DIA.
- 9. FOR SOLDERABILITY SEE AMP PRODUCT SPEC 108-9024.
- 10. .000150 MIN TIN-LEAD IN ZONE 2.
- 11. AREA TO BE UNPLATED (-9 ONLY).
- 12. GOLD FLASH IN ZONE 1.
- 13. .000150 MIN TIN IN ZONE 3.
- 14. GOLD FLASH IN ZONE 1.
- 15. .000150 MIN TIN ENTIRE CONTACT.

SUPERSEDED BY 88997-5

OBSELETE	10/11	88997-9
	10/3/6	88997-5
	10/3/5	88997-4
	10/3/4	88997-3
	10/2/9	88997-2

FINISH	PART NO

THIS DRAWING IS A CONTROLLED DOCUMENT.									
DIMENSIONS:		TOLERANCES UNLESS OTHERWISE SPECIFIED:		P/N: 10A0004		REV: 10A0004		DATE: 10A0004	
INCHES				S. BOLASH		M. WATKINS		10A0004	
		0 P.C. 1 P.C. 2 P.C. 3 P.C. 4 P.C. FINISH		± ± ± ± .006 ± ±		108-9024		114-16015	
MATERIAL: PH. BRONZE .010 THK		SET TABLE		CUSTOMER DRAWING		A2 100779		C=88997	
				SCALE: 10:1		SHEET: 1 OF 1		REV: Y2	
								RESTRICTED TO: —	